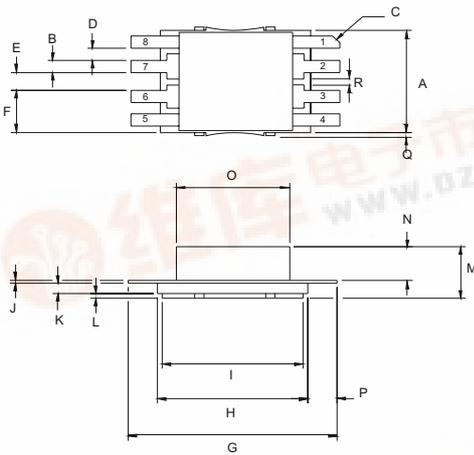


# D2253UK

## METAL GATE RF SILICON FET

### MECHANICAL DATA



#### DBC4 Package

- PIN 1 Source (Common)    PIN 5 Source (Common)
- PIN 2 Drain 1            PIN 6 Gate 2
- PIN 3 Drain 2            PIN 7 Gate 1
- PIN 4 Source (Common)    PIN 8 Source (Common)

DIM	mm	Tol.	Inches	Tol.
A	6.47	0.08	.255	.003
B	0.76	0.08	.030	.003
C	45°	5°	45°	5°
D	0.76	0.08	.030	.003
E	1.14	0.08	.045	.003
F	2.67	0.08	.105	.003
G	11.73	0.13	.462	.005
H	8.43	0.08	.332	.003
I	7.92	0.08	.312	.003
J	0.20	0.02	.008	.001
K	0.64	0.02	.025	.001
L	0.30	0.02	.012	.001
M	3.25	0.08	.128	.003
N	2.11	0.08	.083	.003
O	6.35SQ	0.08	.250SQ	.003
P	1.65	0.51	.065	.020
Q	0.13	max	.005	max
R	0.25	0.07	0.010	.003

# GOLD METALLISED MULTI-PURPOSE SILICON DMOS RF FET 5W – 12.5V – 1GHz PUSH-PULL

### FEATURES

- SIMPLIFIED AMPLIFIER DESIGN
- SUITABLE FOR BROAD BAND APPLICATIONS
- VERY LOW  $C_{rss}$
- SIMPLE BIAS CIRCUITS
- LOW NOISE
- HIGH GAIN – 10 dB MINIMUM

### APPLICATIONS

- VHF/UHF COMMUNICATIONS  
from 1MHz to 1 GHz

### ABSOLUTE MAXIMUM RATINGS (T<sub>case</sub> = 25°C unless otherwise stated)

P <sub>D</sub>	Power Dissipation	15W
BV <sub>DSS</sub>	Drain – Source Breakdown Voltage *	40V
BV <sub>GSS</sub>	Gate – Source Breakdown Voltage *	±20V
I <sub>D(sat)</sub>	Drain Current *	2A
T <sub>stg</sub>	Storage Temperature	-65 to 150°C
T <sub>op</sub>	Maximum Operating Junction Temperature	200°C



**ELECTRICAL CHARACTERISTICS** ( $T_{\text{case}} = 25^{\circ}\text{C}$  unless otherwise stated)

Parameter		Test Conditions		Min.	Typ.	Max.	Unit
<b>PER SIDE</b>							
$BV_{\text{DSS}}$	Drain–Source Breakdown Voltage	$V_{\text{GS}} = 0$	$I_{\text{D}} = 10\text{mA}$	40			V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}} = 12.5\text{V}$	$V_{\text{GS}} = 0$			1	mA
$I_{\text{GSS}}$	Gate Leakage Current	$V_{\text{GS}} = 20\text{V}$	$V_{\text{DS}} = 0$			1	$\mu\text{A}$
$V_{\text{GS(th)}}$	Gate Threshold Voltage*	$I_{\text{D}} = 10\text{mA}$	$V_{\text{DS}} = V_{\text{GS}}$	1		7	V
$g_{\text{fs}}$	Forward Transconductance*	$V_{\text{DS}} = 10\text{V}$	$I_{\text{D}} = 0.2\text{A}$	0.18			S
<b>TOTAL DEVICE</b>							
$G_{\text{PS}}$	Common Source Power Gain	$P_{\text{O}} = 5\text{W}$		10			dB
$\eta$	Drain Efficiency	$V_{\text{DS}} = 12.5\text{V}$	$I_{\text{DQ}} = 0.2\text{A}$	40			%
VSWR	Load Mismatch Tolerance	$f = 1\text{GHz}$		20:1			—
<b>PER SIDE</b>							
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}} = 0$	$V_{\text{GS}} = -5\text{V}$	$f = 1\text{MHz}$		12	pF
$C_{\text{oss}}$	Output Capacitance	$V_{\text{DS}} = 12.5\text{V}$	$V_{\text{GS}} = 0$	$f = 1\text{MHz}$		10	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance	$V_{\text{DS}} = 12.5\text{V}$	$V_{\text{GS}} = 0$	$f = 1\text{MHz}$		1	pF

\* Pulse Test: Pulse Duration = 300  $\mu\text{s}$  , Duty Cycle  $\leq 2\%$

**THERMAL DATA**

$R_{\text{THj-case}}$	Thermal Resistance Junction – Case	Max. 12.0°C / W
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